

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3018542

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
AKIRA MATSUO	08/05/2014
YOSUKE SHIBUYA	08/05/2014
NAOMU KITANO	08/01/2014
EITAROH MORIMOTO	08/04/2014
KOJI YAMAZAKI	08/18/2014
YU SATO	08/05/2014
TAKUYA SEINO	08/05/2014
RECEIVING PARTY DATA	
Name:	CANON ANELVA CORPORATION
Street Address:	2-5-1, KURIGI, ASAO-KU
City:	KAWASAKI-SHI, KANAGAWA
State/Country:	JAPAN
Postal Code:	215-8550
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14327985
CORRESPONDENCE DATA	
Fax Number:	(212)218-2200
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2122182100
Email:	asteensen@fchs.com
Correspondent Name:	JASON M. OKUN
Address Line 1:	FITZPATRICK, CELLA, HARPER & SCINTO
Address Line 2:	1290 AVENUE OF THE AMERICAS
Address Line 4:	NEW YORK, NEW YORK 10104-3800
ATTORNEY DOCKET NUMBER:	03594.014600.
NAME OF SUBMITTER:	JASON M. OKUN
SIGNATURE:	/Jason M. Okun/
DATE SIGNED:	09/11/2014

PATENT

Total Attachments: 6

source=03253PCUSDeclarationandAssignment#page1.tif

source=03253PCUSDeclarationandAssignment#page2.tif

source=03253PCUSDeclarationandAssignment#page3.tif

source=03253PCUSDeclarationandAssignment#page4.tif

source=03253PCUSDeclarationandAssignment#page5.tif

source=03253PCUSDeclarationandAssignment#page6.tif

COMBINED DECLARATION AND ASSIGNMENT
FOR PATENT APPLICATION

(page 1)

Title of Invention: ELECTRONIC COMPONENT MANUFACTURING METHOD AND ELECTRODE
STRUCTURE

As a or the below named inventor, I hereby declare that:

This declaration is directed to:

- The attached application, or
- United States application or PCT international application number

14/327,985

filed on July 10, 2014

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than (5) years, or both.

COMBINED DECLARATION AND ASSIGNMENT
FOR PATENT APPLICATION
(page 2)

FOR VALUE RECEIVED, WE

Akira MATSUO
Yohsuke SHIBUYA
Naomu KITANO
Eitaroh MORIMOTO
Koji YAMAZAKI
Yu SATO
Takuya SEINO

hereby sell, assign, transfer and convey unto CANON ANELVA CORPORATION

a corporation of Japan

having a place of business at 2-5-1, Kurigi, Asao-ku, Kawasaki-shi, Kanagawa 215-8550, Japan

its successors, assigns and legal representatives (hereinafter called the "Assignee"), the entire right, title and interest, for the United States, in and to certain inventions relating to ELECTRONIC COMPONENT MANUFACTURING METHOD AND ELECTRODE STRUCTURE

and described in an application for Letters Patent of the United States filed by us on July 10, 2014 and which has been accorded Application No. 14/327,985

and in and to said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted, thereon, and all reissues and extensions thereof; and we hereby authorize and request the Commissioner for Patents and Trademarks of the United States to issue all Letters Patent upon said inventions to the Assignee or to such nominees as it may designate.

AND we authorize and empower the said Assignee or nominees to invoke and claim for any application for patent or other form of protection for said inventions, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from us.

AND we hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in the United States for any purpose and more particularly in proof of the right of said Assignee or nominees to claim the aforesaid benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

AND we hereby covenant that we have the full right to convey the entire right, title and interest herein assigned and that we have not executed and will not execute any agreement in conflict herewith.

AND we hereby covenant and agree that we will communicate to said Assignee or nominees all facts known to us pertaining to said inventions, and testify in all legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and declarations and in general perform all lawful acts necessary or proper to aid said Assignee or nominees in obtaining, maintaining and enforcing all lawful patent protection for said inventions in the United States.

IN TESTIMONY WHEREOF, We hereunto set our hand:

COMBINED DECLARATION AND ASSIGNMENT
FOR PATENT APPLICATION
(page 3)

Full Name of Sole or First Inventor Akira MATSUO

Inventor's signature Akira Matsuo

Date August 5, 2014

Full Name of Second Joint Inventor Yohsuke SHIBUYA

Inventor's signature Yohsuke Shibuya

Date August 5, 2014

Full Name of Third Joint Inventor Naomu KITANO

Inventor's signature _____

Date _____

Full Name of Fourth Joint Inventor Eitaroh MORIMOTO

Inventor's signature Eitaroh Morimoto

Date August 4, 2014

Full Name of Fifth Joint Inventor Koji YAMAZAKI

Inventor's signature Koji Yamazaki

Date August 18, 2014

Full Name of Sixth Joint Inventor Yu SATO

Inventor's signature Yu Sato

Date August 5, 2014

Full Name of Seventh Joint Inventor Takuya SEINO

Inventor's signature Takuya Seino

Date August 5, 2014

COMBINED DECLARATION AND ASSIGNMENT
FOR PATENT APPLICATION
(page 1)

Title of Invention: ELECTRONIC COMPONENT MANUFACTURING METHOD AND ELECTRODE
STRUCTURE

As a or the below named inventor, I hereby declare that:

This declaration is directed to:

- The attached application, or
 United States application or PCT international application number

14/327,985

filed on July 10, 2014

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than (5) years, or both.

COMBINED DECLARATION AND ASSIGNMENT
FOR PATENT APPLICATION
(page 2)

FOR VALUE RECEIVED, WE Akira MATSUO
 Yohsuke SHIBUYA
 Naomu KITANO
 Eitaroh MORIMOTO
 Koji YAMAZAKI
 Yu SATO
 Takuya SEINO

hereby sell, assign, transfer and convey unto CANON ANELVA CORPORATION
a corporation of Japan

having a place of business at 2-5-1, Kurigi, Asao-ku, Kawasaki-shi, Kanagawa 215-8550, Japan

its successors, assigns and legal representatives (hereinafter called the "Assignee"), the entire right, title and interest, for the United States, in and to certain inventions relating to ELECTRONIC COMPONENT MANUFACTURING METHOD AND ELECTRODE STRUCTURE

and described in an application for Letters Patent of the United States filed by us on July 10, 2014 and which has been accorded Application No. 14/327,985 and in and to said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted, thereon, and all reissues and extensions thereof; and we hereby authorize and request the Commissioner for Patents and Trademarks of the United States to issue all Letters Patent upon said inventions to the Assignee or to such nominees as it may designate.

AND we authorize and empower the said Assignee or nominees to invoke and claim for any application for patent or other form of protection for said inventions, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from us.

AND we hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in the United States for any purpose and more particularly in proof of the right of said Assignee or nominees to claim the aforesaid benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

AND we hereby covenant that we have the full right to convey the entire right, title and interest herein assigned and that we have not executed and will not execute any agreement in conflict herewith.

AND we hereby covenant and agree that we will communicate to said Assignee or nominees all facts known to us pertaining to said inventions, and testify in all legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and declarations and in general perform all lawful acts necessary or proper to aid said Assignee or nominees in obtaining, maintaining and enforcing all lawful patent protection for said inventions in the United States.

IN TESTIMONY WHEREOF, We hereunto set our hand:

COMBINED DECLARATION AND ASSIGNMENT
FOR PATENT APPLICATION
(page 3)

Full Name of Sole or First Inventor Akira MATSUO
Inventor's signature _____
Date _____

Full Name of Second Joint Inventor Yohsuke SHIBUYA
Inventor's signature _____
Date _____

Full Name of Third Joint Inventor Naomu KITANO
Inventor's signature Naomu Kitano
Date August 1, 2014

Full Name of Fourth Joint Inventor Eitaroh MORIMOTO
Inventor's signature _____
Date _____

Full Name of Fifth Joint Inventor Koji YAMAZAKI
Inventor's signature _____
Date _____

Full Name of Sixth Joint Inventor Yu SATO
Inventor's signature _____
Date _____

Full Name of Seventh Joint Inventor Takuya SEINO
Inventor's signature _____
Date _____